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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16578**

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**Issue Date:** 23-Jun-2011

**TITLE:** Qualification of Vigilant Technology, Bangkok, Thailand for Assembly/Test of PDIP7/8 LD

**PROPOSED FIRST SHIP DATE:** 23-Sep-2011

**AFFECTED CHANGE CATEGORY(S):** Subcontractor Assembly/Test Location

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Scott.Brow@onsemi.com](mailto:Scott.Brow@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[Ken.Fergus@onsemi.com](mailto:Ken.Fergus@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This is a Final Product Change Notice to alert customers of the planned qualification of Vigilant Technology, Bangkok, Thailand, (ISO/TS certified) to assemble and test products in PDIP7/8 lead packages. Vigilant will provide additional capacity to supplement ON Semiconductors' current assembly and test facility located at Unisem, Batam, Indonesia. Vigilant is currently qualified for assembly/test to run PDIP8 lead packages within ON Semiconductor.



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**RELIABILITY DATA SUMMARY:**

As there is no change in the bill of materials (BOM) from the products already qualified at Vigilant, the products will qualify by similarity to devices already running in production.

<u>Reliability Summary:</u>		Lot 1	Lot 2	Lot 3
External Visual	40X	0/237	0/237	0/237
Autoclave	121C/15PSI/100%RH/240 Hrs	0/116	0/116	0/116
Temperature Cycle	-65C/+150C, 500 Cy	0/121	0/121	0/121
Wire Bond Inspection	100-500X	0/5	0/5	0/5
Wire Pull		0/5	0/5	0/5

**ELECTRICAL CHARACTERISTIC SUMMARY:**

The electrical specifications will remain identical. A full electrical characterization over temperature will be performed for each device to ensure device functionality and electrical specifications.

**CHANGED PART IDENTIFICATION:**

Devices assembled by Vigilant will include the character 'V' as the identifier in the trace code. Upon expiration of the PCN devices may be sourced from either Vigilant, or previously qualified assembly locations. Manufacturing traceability will be maintained to allow identification of the assembly source.

As Vigilant will be using pre-plated NiPdAu lead frames when compared to the Sn Plating done at Unisem, as per JESD97, May 2004, section 5 the following information will be included to indicate the appropriate Pb-free 2<sup>nd</sup> level interconnect:

- Package labeling for material assembled in Vigilant will state 'e4', to indicate the use of precious metals, no Sn
- Package labeling for material assembled in previously qualified assembly locations will state 'e3' to indicate the use of Sn.



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**List of affected General Parts:**

NCP1203P100G  
NCP1203P60G  
NCP1203P40G  
NCP1200P60G  
NCP1200P100G  
NCP1200P40G  
NCP1207APG  
NCP1230P100G  
NCP1230P133G  
NCP1230P65G